

LAPP electronics developments

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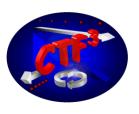




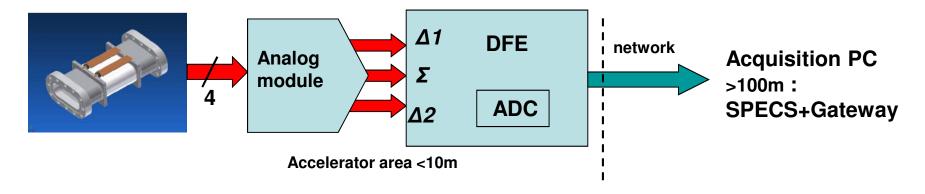




1- LAPP in CTF3: principles



<u>Aim:</u> reduction of costs of long analog cables/VME ADCs - idea that future electronics should be close to the beam → Rad-hard acquisition electronics close to beam.



Analog module: Intensity & deviations processing BPI or BPM.

DFE board:

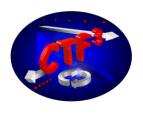
- sampling 3 channels, 12 bits / 500MSps.
- Feed-back for analog modules: gains, calibration and attenuations.
- Daisy chain acquisition: 1 network cable per crate (~4 boards per crate).

Acquisition PC: FESA-OASIS soft and specialist requirements feed-back.

→ Cost divided by a factor 3 comparing to a « far » acquisition.



1- LAPP in CTF3: results



From November 2006 to summer 2009: production and installation of 47 analog modules and 46 DFE boards distributed in 12 crates in TL1, CR, TL2 and CLEX.

Acquisition of BPM, BPI and BPS.

Man power: ~2,5men/year FTE since September 2005

IN2P3 funding: ~100k€.

Results: OK but recurrent problems of noise and data transmission.





Motivations for a new development:

We met problems with analog memory sampling and network transmissions. Logical evolution dedicated to a larger accelerator as CLIC:

Rare acces from surface, high number of channels, rad-hard, low-cost, low consumption, all-around accelerator standard acquisition....

We got experience and we are committed in accelerators.

Since spring 2009:

first discussion with CTF3, definition of possible future solutions:

- → elimination of last copper links: use of optical link network.
- → A crate including ~ 6 acquisitions, 1calibration, 1power supplies, 1network switch.

Selection of 2 ADCs, design of an evaluation board.

→ last summer tests and specifications discussions have concluded to a 100Msps/12 ENOB solution.

Design of a local calibration current generator with a first prototype last summer.

→ Tests validated the solution: adjustable up to 10A pulse.

Tests on optical links shown the possibility to use the carrier to transmit the machine clock.



It brought to a meeting with CLIC for a definition of possible collaboration.

CLIC and CTF3 needs are converging: 4 objects to acquire per module or crate.

As these objects are hard to define now, our approach is to propose a "state-of-the-art" solution which could be a first step to a larger acquisition system: a paper is being currently finalized.

A meeting with CLIC based on this proposal is foreseen next month to fix the bases of the collaboration.

Last studies fixed a simpler architecture proposal:

Single acquisition board 4X4 channels possible for the whole module:

- → direct electrode sampling: no more analog module.
- → only one acquisition board, only one FPGA, only one SFP link.
- → huge cost reduction: components, PCBs, hardware...
- → no more local crate collection board (switch): one less network level, no more front panel cabling.



Next crate simpler:

4X4 Acquisition board directly linked to the network.

Calibration board controlled by the FPGA.

Autonomous power supplies.

Acquisition board: 4 quad ADCs, 1 FPGA.

Foreseen sampling: 100Msps (10ns), 14bits, 12ENOB.

- → Quad ADCs allow good CMRR and low clock skew between channels.
- → Simple analog stage: attenuation/gain before ADC.

Possible local <u>FPGA processing:</u> deviations, averages, auto-trigger, droop compensation...

- <u>Calibration board:</u> adjustable current pulse up to 10A.
 - → Regulation using a µcontroller linked to ADC FPGA.
 - → output multiplexing 1 current to 8 electrodes.
 - → disabled when not used to limit power consumption & EMI problems.



- Autonomous power supplies: local AC-DC converter from 220V line to 12VDC.
- Network: in both case of synchronous or asynchronous acquisition with machine clock, we think that the network should be in a tree configuration:

Broadcast descending network.

Point-to-point ascending network.

→ needs to be connected and compatible with the future solution supported by CERN as White Rabbit.

First step: development of a PCI-express transmission board.

Second step: development of a data collection board (switch) for network tree.

Radiations issues: the choice of rad-hard components is very reduced;

- → use of components known for their rad-tolerance.
- → digital with specific design techniques: triple voting, small technos...
- → CTF3 will be a good test area.
- → Qualification based on specifications in the future.
- → Infrastructure possibilities have to be studied.



Milestones

End 2009: definition of the collaboration, final technical discussions.

Mid 2010: crate with ADC board, calibration, power supplies.

Tests and debug with already existing evaluation PCI board.

Fall 2010: PCIe network board.

Tests and debug of the full chain, tests in CTF3.

Could update the current CTF3 acquisition.

Fall 2011: local network switch.

LAPP resources:

for the next two years 3 men FTE and IN2P3 funding ~30k€/year.

CTF3 is a first step and the good place to develop such a system.